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Recommended Soldering Profile for Rectifier Diodes (Pb Free)

a) Wave Soldering Profile





Recommended Soldering Profile for Rectifier Diodes (Pb Free)

b) Reflow Soldering Profile (Pb free Application), refer to IPC/JEDEC J-STD-020





Recommended Soldering Profile for Rectifier Diodes (Pb Free)

Preheat/Soak Temperature Min (Tsmin) Temperature Max (Tsmax) Time (ts) from (Tsmin to Tsmax)	50 °C 200 °C 60-120 seconds
Melting Point of Solder (Sn Ag Cu)	217°C
Ramp-up Rate to 217°C(Melting Point of Solder)	3°C/sec
Time at Temp.>217°C (Melting Point of Solder)	60~150 Sec
Peak Temperature	255±5℃
Time within 5°Cbelow Peak Temp.	20~40 Sec
Cooling Rate	6°C/sec (max)
Time from 25°C to Peak Temp.	8min (max)